



## Advanced Product / Process Change Notice

No.: Z200-APCN-DM201607-02-P

Date: 07/22/2016

**Change Title : W25Q32JV "J-Series" (58nm) to replace W25Q32FV "F-Series" (58nm) 32Mb SpiFlash® Memories**

Change Classification:  Major  Minor

Change item :  Design  Raw Material  Wafer FAB  Assembly  Packing  Testing  Others

**Affected Product(s) :**

W25Q32FVSSIF ,W25Q32FVSSIG ,W25Q32FVSSIQ ,W25Q32FVSFIG ,W25Q32FVSFIQ ,W25Q32FVDAIG,  
W25Q32FVDAIQ ,W25Q32FVZPIG ,W25Q32FVZPIQ ,W25Q32FVTBIG ,W25Q32FVTCIG

**Description of Change(s) :**

The W25Q32JV 32Mb SpiFlash® Memories use Winbond's 58nm Flash technology. It is function-compatible with W25Q32FV 58nm devices offering improved performance, features and availability. (Please refer attachment I)

**Reason for Change(s) :**

Improve features and Command backward compatible with W25Q32FV.

**Impact of Change(s) : ( positive & negative )**

Form : No Change

Fit : No Change

Function : No Concern (Please refer to attachment I)

Reliability : On-going (Expected come out Aug/15/2016)

Hazardous Substances: On-going (Expected come out Aug/15/2016)

**Qualification Plan/ Results :**

The qualification and Hazardous Reports are in progress and expected come out in Aug/15/2016.

**Implementation Plan :**

Please refer to Attachment II for details.

Date Code: \_\_\_\_ onward  Lot No: \_\_\_\_ onward  Proposed first ship date: 10/24/2016

**Originator: (QA)**

Hyhuang

**Approval: (QA Dept. Manager)**

YH Chang

**Approval: (QRA Director)**

Gen Chen

**Contact for Questions & Concerns**

Name: Betty Huang TEL:886-3-5678168 (ext.86549) FAX:886-3-5796124  
Address : # 539, Sec. 2, Wenxing Rd., Jhubei City, Hsinchu County 302, Taiwan  
E-mail: Hyhuang8@winbond.com



**Customer Comments:**

*Note: Please sign this notice, and return to Winbond contact within 30 days. If no response is received within 30 days, this Change Request will be assumed to meet your approval.*

Approval       Disapproval       Conditional Approval : \_\_\_\_\_.

Comment:

Date: \_\_\_\_\_

Dept. name: \_\_\_\_\_

Person in charge: \_\_\_\_\_



***winbond***

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# Comparison table (W25Q32JV vs W25Q32FV)

Nov.2015



# Comparison table

<b>3V 64Mb-bit</b>				
	<b>Product Number</b>		<b>W25Q32FV</b>	<b>W25Q32JV</b>
General				
	Density		32Mb	32Mb
	Power Supply		2.7~3.6V	2.7~3.6V
	Temperature		-40~85°C	-40~85°C
	Max. Fast Read Frequency		104MHz	104MHz
	Max. Normal Read Frequency		50MHz	50MHz
	Special OTP		v	v
DC			Typical/Max.	Typical/Max.
	ICC1	Standby Current	10μA/50μA	10μA/50μA
	ICC2	Power-Down Current	1μA/20μA	1μA/15μA
	ICC3	Data Read Current (50MHz)	15mA	15mA
	ICC3	Data Read Current (80MHz)	18mA	18mA
	ICC3	Data Read Current(104MHz)	20mA	20mA
	ICC5	Current Page Program	20mA/25mA	20mA/25mA
	ICC6	Current Sector/Block Erase	20mA/25mA	20mA/25mA
	ICC7	Current Chip Erase	20mA/25mA	20mA/25mA



	Product Number		W25Q32FV	W25Q32JV
AC				
	tCLH/tCLL	Clock High/Low Time	4ns	3.47ns
	tSHSL(tCSH)	/CS Deselect Time ( Array / SR or ID)	50ns	50ns
	tCLQV	Clock Low to Output Valid(max)	7ns	6ns
	tWHSL	Write Protect Setup Time Before /CS L	20ns	20ns
	tSHWL	Write Protect Hold Time After /CS High	100ns	100ns
	tW	Write Status Register Time	10m/15ms	10m/15ms
	tPP	Page Program Time	0.7ms/3ms	0.7ms/3ms
	tSE	Sector Erase Time (4KB)	45ms/400ms	45ms/400ms
	tBE1	Block Erase Time (32KB)	120/1600ms	120/1600ms
	tBE2	Block Erase Time (64KB)	150/2000ms	150/2000ms
	tCE	Chip Erase Time	10/50s	10/50s
Command			W25Q32FV	W25Q32JV
	Write Enable		06h	06h
	Write Disable		04h	04h
	Read Status Register-1		05h	05h
	Write Status Register-1		01h	01h
	Page Program		02h	02h
	Sector Erase (4KB)		20h	20h
	Block Erase (32KB)		52h	52h
	Block Erase (64KB)		D8h	D8h



	Block Erase (64KB)	D8h	D8h
	Chip Erase	C7h/60h	C7h/60h
	Power-down	B9h	B9h
	Read Data	03h	03h
	Fast Read	0Bh	0Bh
	Fast Read Dual Output	3Bh	3Bh
	Fast Read Dual I/O	BBh	BBh
	Release Power down/ Device ID	ABh	ABh
	Manufacturer/Device ID	90h	90h
	Manufacturer/Device ID by Dual I/O	92h	92h
	Enable Reset	66h	66h
	Reset Device	99h	99h
<b>ID</b>			
	Manufacturer ID	EFh	EFh
	Device ID (ABh, 90h)	15h	15h
	JEDEC ID (9Fh)	4016h	4016h



**Winbond Electronics Corporation**

6F., No.38, Gaotie 1st Rd., Jhubei City,  
Hsinchu County 30273, Taiwan R.O.C.

**Product Obsolescence Notice**

**W25Q32JV SpiFlash Memories**

Notification Date: July, 21, 2016

Dear Valued Customer,

This letter is to notify you of Winbond’s intention to terminate production of the W25Q32FV SpiFlash memory, and replace it with the W25Q32JV. Replacement part numbers are listed below:

Winbond Current PN (58nm D-Series)	Winbond Primary Replacement PN (58nm J-Series)
W25Q32FVSSIG W25Q32FVSSIQ W25Q32FVSSIF	W25Q32JVSSIQ
W25Q32FVSFIG W25Q32FVSFIQ	W25Q32JVSFIQ
W25Q32FVDAIG W25Q32FVDIAIQ	W25Q32JVDAIQ
W25Q32FVZPIG W25Q32FVZPIQ	W25Q32JVZPIQ
W25Q32FVTBIG	W25Q32JVTBIQ
W25Q32FVTCIG	W25Q32JVTCIQ

The W25Q32JV device features:

**Features**

- a) Command backward compatible with W25Q32FV (same Superset Instruction Set)
- b) Clock operation up to 133MHz
- c) Lower power consumption
- d) SPI with Single / Dual / Quad
- e) Flexible architecture with 4KB sectors

Please refer to the table below for your particular product last time order date and Winbond last shipment date and use this table to determine your last time buys and subsequent request dates. Winbond Electronics reserves the right to limit last time buy quantities based on capacity and material availability. Please notify Winbond as soon as possible if there are any concerns with these this schedule.

Part Number	Notification Date	Last Order Date	Last Ship Date	Part Number	Reliability Report	Mass Production
W25Q32FV	Jul./21/ 2016	Jan./21/ 2017	Jul./21/ 2017	W25Q32JV	Aug./15/ 2016	Mar./24/ 2016



*Eddy Hung*

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Eddy Hung

Assistant Vice President of Flash Marketing





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**Affected Products**

As below:

<b>Winbond Current PN (58nm D-Series)</b>	<b>Winbond Primary Replacement PN (58nm J-Series)</b>
W25Q32FVSSIG W25Q32FVSSIQ W25Q32FVSSIF	W25Q32JVSSIQ
W25Q32FVSFIG W25Q32FVSFIQ	W25Q32JVSFIQ
W25Q32FVDAIG W25Q32FVD AIQ	W25Q32JVDAIQ
W25Q32FVZPIG W25Q32FVZPIQ	W25Q32JVZPIQ
W25Q32FVTBIG	W25Q32JVTBIQ
W25Q32FVTCIG	W25Q32JVTCIQ